/ Absolute Maximum Ratings(Ta=25)

v Ώ Parameter	ү ᴺ Symbol	ΏӪ Rating	ᴅ ɧ Unit
Peak pulse power (t_p = 8/20μs)	P_K	69	W
Peak pulse current (t_p = 8/20μs)	I_{PP}	5.5	A
ESD according to IEC61000-4-2 air discharge	V_{ESD}	±30	KV
ESD according to IEC61000-4-2 contact discharge		±30	
Junction temperature	T_J	150	
Storage temperature	T_{STG}	-55~+150	

/ Electrical Characteristics(Ta=25)

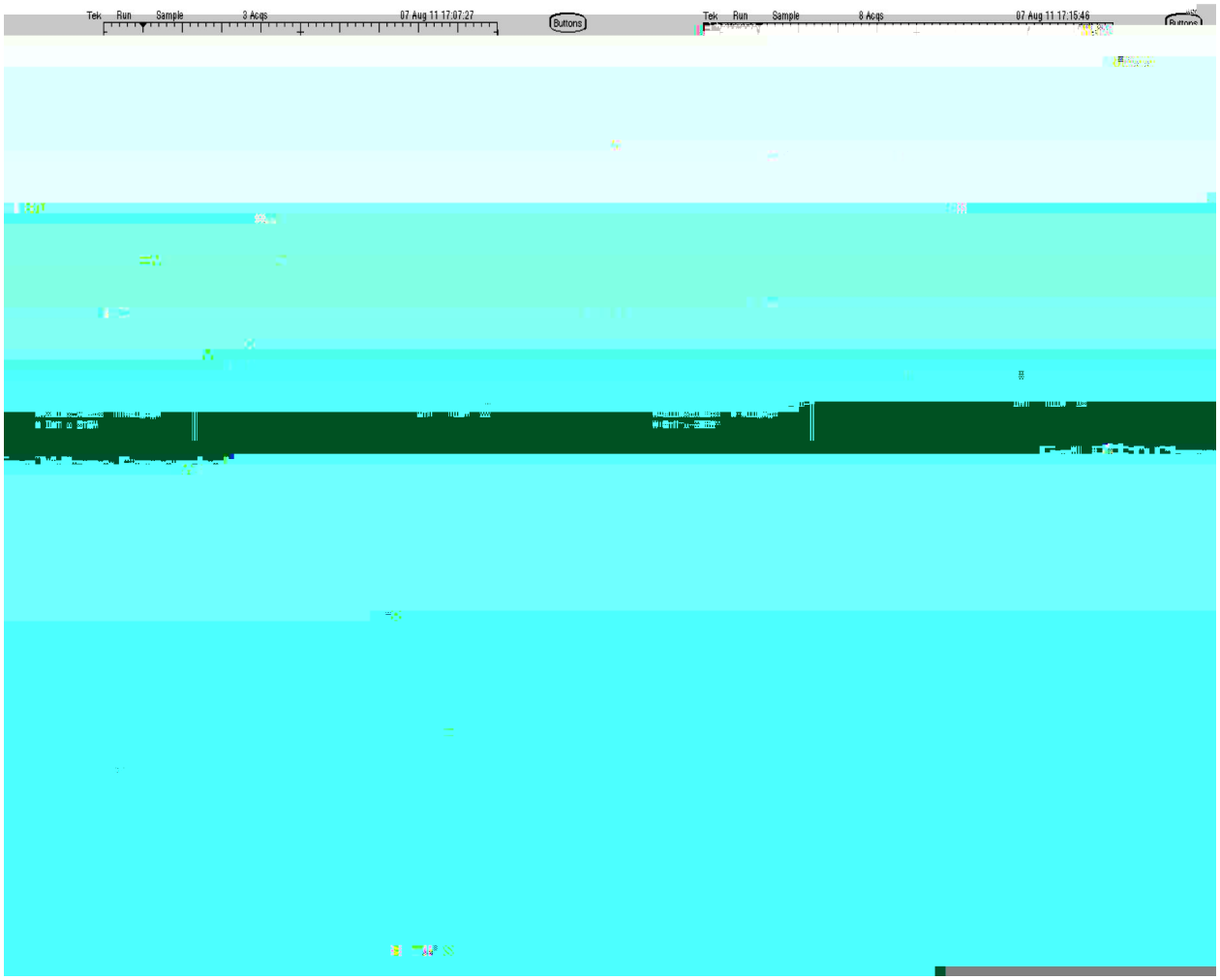
v Ώ Parameter	ү ᴺ Symbol	╜ ꜝᛏ Ʈ Test Conditions	ῳ ꞃ Ӫ Min	Ɛ ʒ Ӫ Typ	ῳ ᶾ Ӫ Max	ᴅ ɧ Unit
Reverse maximum working voltage	V_{RWM}				3.3	V
Reverse leakage current	I_R	V_{RWM} =3.3V			0.1	uA
Reverse breakdown voltage[1)]	V_{BR}	I_T = 1mA	5.0		6.8	V
Clamping voltage [2)]	V_C	I_{PP} = 1A t_p = 8/20μs			9.8	V
		I_{PP} = 5.5A t_p = 8/20μs			12.5	V
Junction capacitance	C_J	V_R = 0V f = 1MHz			15	pF

Notes:

1) V_{BR} is measured with a pulse test current IT at an ambient temperature of 25 ł .

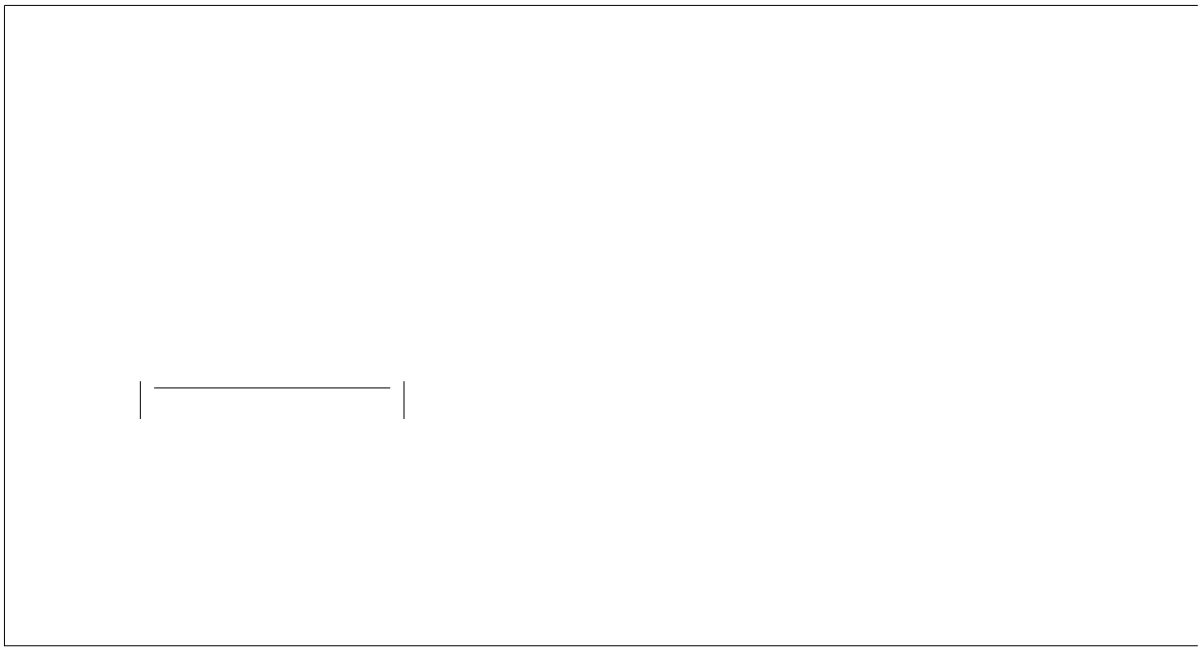
2) Non-repetitive current pulse, according to IEC61000-4-5.

/ Electrical Characteristic Curve

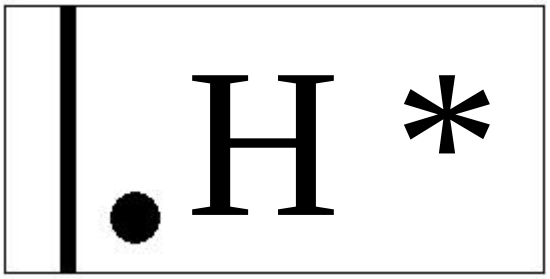


/ Package Dimensions

DFN0603 Unit:mm



/ Marking Instructions



ᑌ ᐟ χ

K χ ᑲᖫ ᖘ ᑎᑐ

- χ ᑲᖫ ᑊ ᖮ ᖕ ᑎᑐ ᑊ ᓀ ᑊ ᖮ ᖕ ᑎ ᖴ ᑭ

Note χ

H χ Product Type

* χ Lot No. Code,code change with Lot No

( ) / Temperature Profile for IR Reflow Soldering(Pb-Free)

ب ˝ χ

1 Ĺ ♬ □ ẙ 150 Ḱ 180 ɬ ı `H ژ 60 Ḱ 90sec;

2 Š Ө □ ẙ 245 ° 5 ɬ ı `H ژ `Y ʌ ʁ 5 ° 0.5sec;

3 ì ˙ ٢ ˛ ɔ ﻩ ẙ ʁ 2 Ḱ 10 ɬ /sec.

Note:

1.Preheating:150~180 ɬ , Time:60~90sec.

2.Peak Temp.:245 ° 5 ɬ , Duration:5 ° 0.5sec.

3. Cooling Speed: 2~10 ɬ /sec.

/ Resistance to Soldering Heat Test Conditions

605 ° 5 ɬ